

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

1. (Amended) A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers[, characterized in that] comprising:

a plurality of plain layers [are] formed as said conductor layers; and
mesh holes [are] formed in said plurality of plain layers so that at least part of the mesh holes overlay [on] one another.

2. (Amended) A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, [characterized in that] comprising:

a plain layer serving as a conductor layer [is] formed on one side of said core substrate;

a plain layer [is] formed out of at least one of the conductor layers formed between said interlayer resin insulating layers; and

mesh holes [are] formed in the plain layer of said core substrate and the plain layer between said interlayer resin insulating layers so that at least part of the mesh holes overlay [on] one another.

3. (Amended) The multilayer build-up wiring board [according to] of claim 1 [or 2], [characterized in that] wherein a diameter of each of said mesh holes is set at 75 to 300 μm and a distance between the mesh holes is set at 100 to 1500 μm

4. (Amended) A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on which a chip is mounted on an outermost layer and having the conductor layers connected to each other by via holes, respectively [characterized in that] comprising:

mesh holes [are] provided in plain layers formed as said conductor layers[.]; and

lands of through holes or the via holes [and the via holes are] provided in at least part of the mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

5. (Amended) A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on an outermost layer and having the conductor layer connected to each other by via holes, respectively, [characterized in that] comprising:

mesh holes [are] provided in plain layers formed as said conductor layers[,]; and
lands of the via holes [are] provided in at least part of the mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

6. (Amended) A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on an outermost layer [characterized in that] comprising:

mesh holes [are] provided in plain layers formed as said conductor layers[,]; and
solid conductor layers [are] provided in at least part of the mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

7. (Amended) A multilayer build-up wiring board wherein interlayer resin insulating layers and conductor layers are alternately provided on a substrate having through holes and a chip mount region for mounting a chip [is] provided on an outermost layer, [characterized in that] comprising:

mesh holes [are] provided in plain layers formed as said conductor layers[,]; and
lands of the through holes [are] provided in at least part of the mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

8. (Amended) A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate, [characterized in that] wherein one of said via holes is formed out of a plurality of wiring paths.

9. (amended) A multilayer build-up wiring board having a multilayer wiring layer, wherein the interlayer resin insulating layer and conductor layer are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate[, characterized in that] wherein, one of said via holes is formed out of two wiring paths.

10. (Amended) a multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate, said conductor layers electrically connected to conductor layers on a back side of the core substrate by through holes formed in the core substrate, respectively [characterized in that] comprising:

a plurality of wiring paths [are] provided in each of the through [hole] holes in said core substrate; and

via holes consisting of a plurality of wiring paths each connected to each of said wiring paths of said through holes [are] provided right on said through holes in which said plurality of wiring paths are provided.

11. (Amended) a multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, the multilayer wiring layer formed on both sides of a core substrate, conductor layers of the both sides of said core substrate electrically connected to one another by through holes formed in the core substrate, [characterized in that] comprising:

a plurality of wiring paths [are] provided in each of the through holes in said core substrate; and

via holes consisting of a plurality of wiring paths each connected to each of said wiring paths of said through hole [are] provided right on said through holes in which said plurality of wiring paths are provided.

12. (Amended) a multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, the multilayer wiring layer

formed on both sides of a core substrate electrically connected to one another by through holes formed in the core substrate, [characterized in that] comprising:

a filler [is] filled in the through holes of said core substrate and a conductor layer covering an exposed surface of the filler from the through holes [is] formed in the through hole; the through holes and the conductor layers [are] divided into a plurality of parts, respectively; and

via holes consisting of wiring paths connected to the divided parts of the conductor layers, respectively, [are] provided right on the through holes covered with said divided parts of the conductor layers.

13. (Amended) A wiring board having a conductor circuit including a conductor layer of two-layer structure in which a second metal film thinner than a first metal film is provided on said first metal film, [characterized in that] comprising:

sides of the second metal film forming said conductor layer [protrude] protruding farther outside said conductor layer than [compared with sides of] said first metal film[.], resin insulating layers provided on the conductor layers.

14. (Amended) A multilayer build-up wiring board having a structure in which at least one resin insulating layer and at least one conductor circuit [are] is formed on a resin substrate, [characterized in that] comprising:

at least one layer of said conductor circuit [includes] including a conductor layer of a two layer structure in which a second metal film thinner than a first metal film is provided on said first metal film; and

sides of the second metal film forming said conductor layer [protrude] protruding farther outside said conductor layer than [compared with sides of] said first metal film.